Rochester Electronics

SPACE LEVEL S/V FLOWS

Devices are processed to the Class V requirements specified in MIL-PRF-38535 and SMD detailed drawings.

*Performed at Rochester's Newburyport campus when appropriate. **Performed at Rochester's Newburyport campus.

START

- *WAFER TRACEABILITY and DESIGN VERIFICATION
- > *WAFER LOT ACCEPTANCE
- > *OUTGOING QA INSPECT
- * Assembly House INCOMING QAINSPECT
- > *WAFER SAW and DIE PREP
- *SECOND OPTICAL INSPECTION (Condition A)
- > *QA LOT ACCEPTANCE
- > *FRAME ATTACH
- > * DIE ATTACH
- > *DIE ATTACH CURE
- > *WIRE BOND
- > *NON-DESTRUCT BOND PULL
- > *THIRD OPTICAL INSPECTION
- > * QA LOT ACCEPTANCE Rochester FIELD SOURCE SURVEILLANCE LOT ACCEPTANCE (optional)
- > *PRE-SEAL BAKE and VACUUM PRE-WELD BAKE (TO type package only)
- > *HERMETIC SEAL/WELD

- *TEMPERATURE CYCLING
- *CONSTANT ACCELERATION
- PARTICAL NOISE DETECTION (PIND)
- > *LEAD TRIM (if applicable)
- > *SOLDER DIP LEAD FINISH and INSPECTION
- *MARK and CURE (optional sequence)
- > **SERIALIZATION
- **RADIOGRAPHY (X-RAY)
- * FINE LEAK SEAL TEST
- > *GROSS LEAK SEAL TEST
- *VISUAL and PACKAGE LOAD
- > *QALOT ACCEPTANCE
- > *SHIP
- > **INCOMING QA LOT ACCEPTANCE

- **Test Lab INCOMING INSPECT
- > **INITIAL ELECTRICAL TEST
- > **BURN IN (240 HRS at 125° C Minimum)
- > **SURVEILLANCE LOT ACCEPTANCE (Optional)
- **ELECTRICAL TEST INTERIM and FINAL
- > **QUALITY CONFORMANCE INSPECTION Group A
- > **FINE/GROSS LEAK
- > **EXTERNAL VISUAL
- > **QUALITY CONFORMANCE INSPECTION Groups B, C, and D
- > **FINAL QA LOT ACCEPTANCE
- **TRANSFERTO STOCK

FINISH

ROCHESTER ELECTRONICS, LLC

WORLDWIDE CORPORATE HEADQUARTERS
16 Malcolm Hoyt Drive – Newburyport, Massachusetts 01950 USA

978.462.9332 phone – 978.462.9512 fax

sales@rocelec.com

